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MC100E310

5 V ECL Low Voltage 2:8 Differential Fanout Buffer

Description

The MC100E310 is a low voltage, low skew 2:8 differential ECL fanout buffer designed with clock distribution in mind. The device features fully differential clock paths to minimize both device and system skew. The E310 offers two selectable clock inputs to allow for redundant or test clocks to be incorporated into the system clock trees.

The lowest TPD delay time results from terminating only one output pair, and the greatest TPD delay time results from terminating all the output pairs. This shift is about 10–20 pS in TPD. The skew between any two output pairs within a device is typically about 25 nS. If other output pairs are not terminated, the lowest TPD delay time results from both output pairs and the skew is typically 25 nS. When all outputs are terminated, the greatest TPD (delay time) occurs and all outputs display about the same 10–20 ps increase in TPD, so the relative skew between any two output pairs remains about 25 ns.

For more information on using PECL, designers should refer to ON Semiconductor Application Note [AN1406/D](#).

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The 100 Series Contains Temperature Compensation.

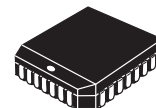
Features

- Dual Differential Fanout Buffers
- 200 ps Part-to-Part Skew
- 50 ps Output-to-Output Skew
- 28-lead PLCC Packaging
- Q Output will Default LOW with Inputs Open or at V_{EE}
- PECL Mode Operating Range: $V_{CC} = 4.2$ V to 5.7 V with $V_{EE} = 0$ V
- NECL Mode Operating Range: $V_{CC} = 0$ V with $V_{EE} = -4.2$ V to -5.7 V
- Internal Input 50 k Ω Pulldown Resistors
- ESD Protection:
 - ◆ > 2 kV Human Body Model
 - ◆ > 200 V Machine Model
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity: Level 3 (Pb-Free)
(For Additional Information, see Application Note [AND8003/D](#))
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 212 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



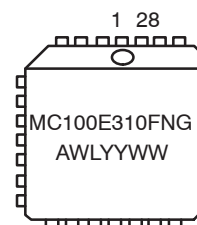
ON Semiconductor®

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PLCC-28
FN SUFFIX
CASE 776-02

MARKING DIAGRAM*



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

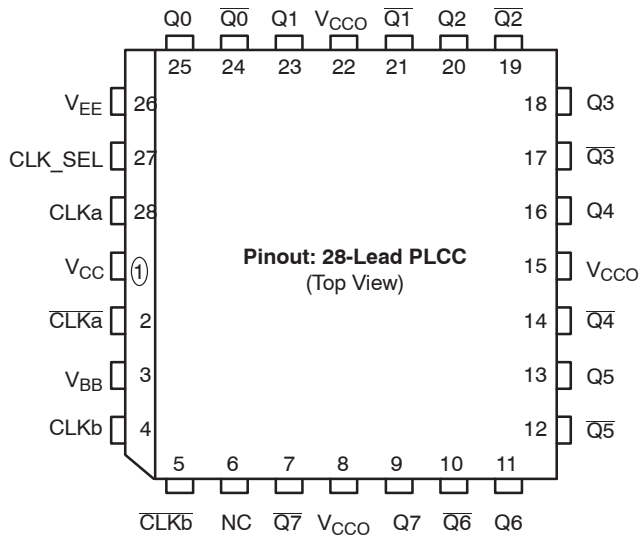
*For additional marking information, refer to Application Note [AND8002/D](#).

ORDERING INFORMATION

Device	Package	Shipping†
MC100E310FNG	PLCC-28 (Pb-Free)	37 Units / Tube
MC100E310FNR2G	PLCC-28 (Pb-Free)	500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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* All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Logic Diagram and Pinout Assignment

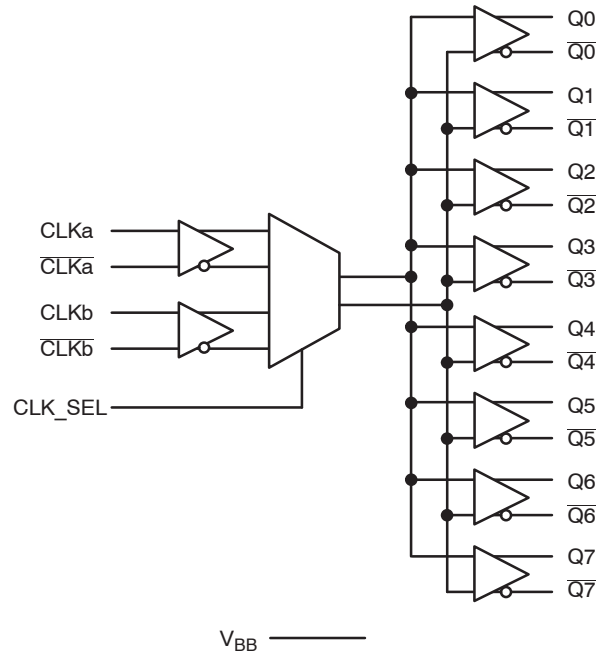


Figure 2. Logic Symbol

Table 1. PIN DESCRIPTION

PIN	Function
CLKa, CLKb; CLKa, CLKb	ECL Differential Input Pairs ECL Differential Input Pairs
Q0:7; Q0:7	ECL Differential Outputs
CLK_SEL	ECL Input Clock Select
V _{BB}	Reference Voltage Output
V _{CC} , V _{CCO}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect

Table 2. FUNCTION TABLE

PIN	Function
0	CLKa Selected
1	CLKb Selected

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Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	$V_{EE} = 0\text{ V}$		8	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	$V_{EE} = 0\text{ V}$ $V_{CC} = 0\text{ V}$	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 -6	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_A	Operating Temperature Range			-40 to +85	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range			-65 to +150	$^{\circ}\text{C}$
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	PLCC-28 PLCC-28	63.5 43.5	$^{\circ}\text{C}/\text{W}$ $^{\circ}\text{C}/\text{W}$
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	PLCC-28	22 to 26	$^{\circ}\text{C}/\text{W}$
T_{sol}	Wave Solder (Pb-Free)			265	$^{\circ}\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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Table 4. 100E SERIES PECL DC CHARACTERISTICS ($V_{CCx} = 5.0\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		55	60		55	60		65	70	mA
V_{OH}	Output HIGH Voltage (Note 2)	3915	3995	4120	3975	4050	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 2)	3170	3305	3445	3190	3255	3380	3190	3260	3380	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	3835	3975	4120	3835	3975	4120	3835	3975	4120	mV
V_{IL}	Input LOW Voltage (Single-Ended)	3190	3355	3525	3190	3355	3525	3190	3355	3525	mV
V_{BB}	Output Voltage Reference	3.62		3.74	3.62		3.74	3.62		3.74	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.7		4.6	2.7		4.6	2.7		4.6	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $-0.46\text{ V} / +0.8\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$.
3. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} .

Table 5. 100E SERIES NECL DC CHARACTERISTICS ($V_{CCx} = 0\text{ V}$; $V_{EE} = -5.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		55	60		55	60		65	70	mA
V_{OH}	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-950	-880	-1025	-950	-880	mV
V_{OL}	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1745	-1620	-1810	-1740	-1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1165	-1025	-880	-1165	-1025	-880	-1165	-1025	-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1810	-1645	-1475	-1810	-1645	-1475	-1810	-1645	-1475	mV
V_{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	-2.3		-0.4	-2.3		-0.4	-2.3		-0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary $-0.46\text{ V} / +0.8\text{ V}$.
2. Outputs are terminated through a $50\ \Omega$ resistor to $V_{CC} - 2.0\text{ V}$.
3. V_{IHCMR} min varies 1:1 with V_{EE} , max varies 1:1 with V_{CC} .

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Table 6. AC CHARACTERISTICS ($V_{CCx} = 5.0\text{ V}$; $V_{EE} = 0\text{ V}$ or $V_{CCx} = 0\text{ V}$; $V_{EE} = -5.0\text{ V}$ (Note 1))

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Maximum Toggle Frequency	700	900		700	900		700	900		MHz
t_{PLH} t_{PHL}	Propagation Delay to Output IN (differential) (Note 2) IN (single-ended) (Note 3)	525 500		725 750	550 550		750 800	575 600		775 850	ps
t_{skew}	Within-Device Skew (Note 4) Part-to-Part Skew (Diff)			75 250			50 200			50 200	ps
t_{JITTER}	Random Clock Jitter (RMS)		< 1			< 1			< 1		ps
V_{PP}	Input Voltage Swing (Differential Configuration)	500			500			500			mV
t_r/t_f	Output Rise/Fall Time (20%–80%)	200		600	200		600	200		600	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. V_{EE} can vary -0.46 V / $+0.8\text{ V}$.
2. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals. See *Definitions and Testing of ECLinPS AC Parameters* in Chapter 1 (page 1–12) of the ON Semiconductor High Performance ECL Data Book (DL140/D).
3. The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
4. The within-device skew is defined as the worst case difference between any two similar delay paths within a single device.

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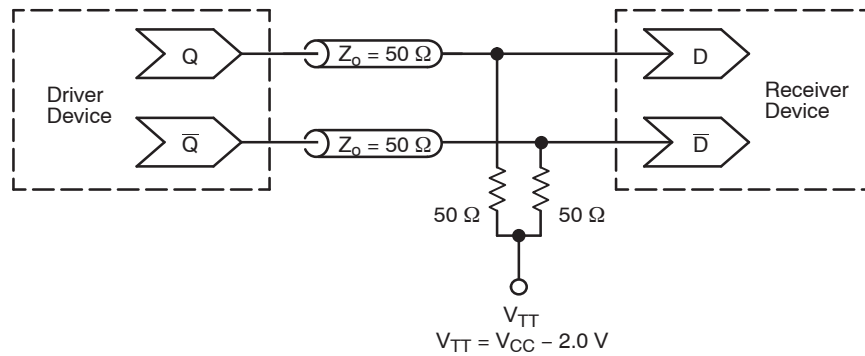


Figure 3. Typical Termination for Output Driver and Device Evaluation
(See Application Note [AND8020/D](#) – Termination of ECL Logic Devices)

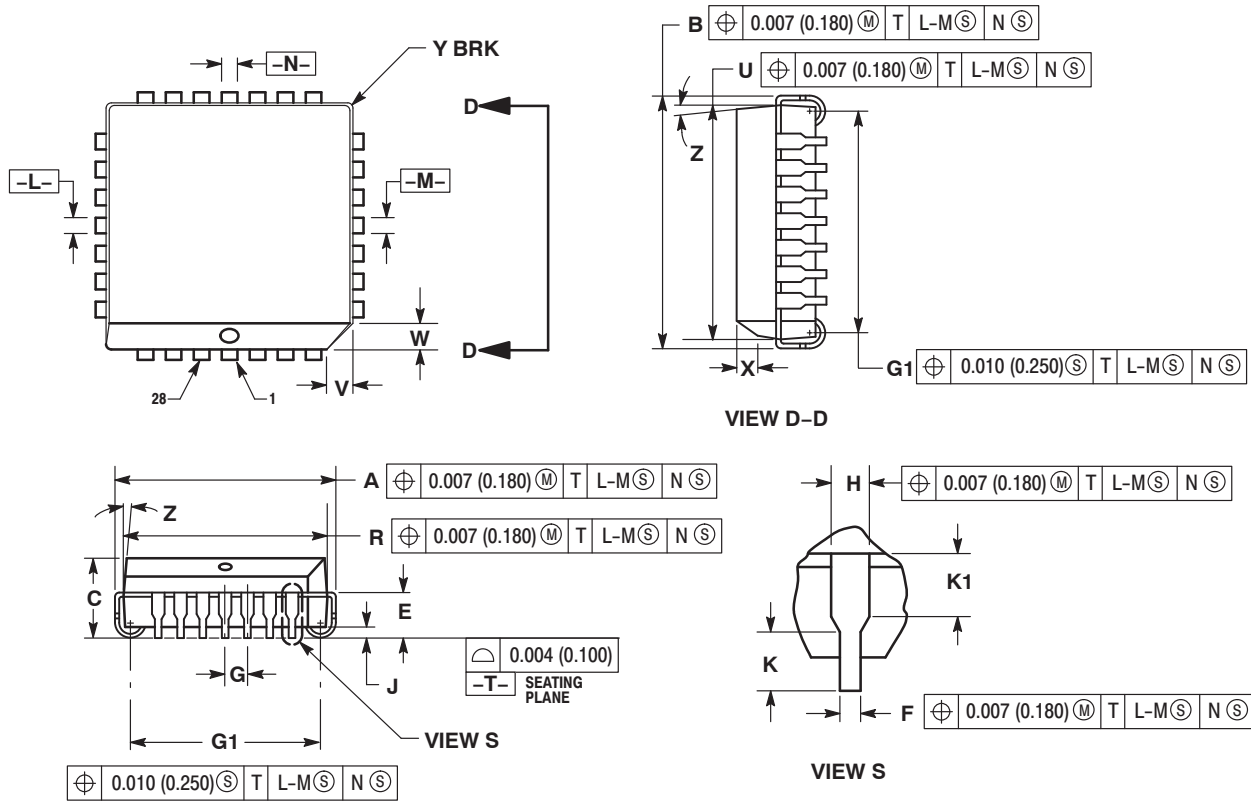
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

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PACKAGE DIMENSIONS

28 LEAD PLLC
FN SUFFIX
CASE 776-02
ISSUE F




NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

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